ABSTRACT

METHOD OF PACKAGING AN INTEGRATED CIRCUIT DEVICE

A method of packaging a bumped electronic chip or a bumped wafer by utilising a combination of two different encapsulants. The first encapsulant (low CTE encapsulant) contains an adhesive filled with a CTE-reducing filler. The second encapsulant (fluxing encapsulant) contains an adhesive containing a fluxing agent or a precursor of a fluxing agent. The low CTE encapsulant is applied directly onto the bumped surface of a wafer before singulation into chips. The fluxing encapsulant is applied onto the substrate. The chip and the substrates are then joined together to form a package.

FIGURES 1A-1D